IV Glossary

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Insulation Displacement Termination/Connection (IDT/IDC) A mechanical termination technique in which a wire is forced into a specially designed slot in a terminal to displace the wire insulation and make an electrical contact to the conductor.	23, 140
Injection Molding: A manufacturing process in which liquid thermoplastic polymer is injected into a heated mold and cooled into a desired part configuration.	59
Integrated Magnetics	288
Interface	287
Intermetallic Compound: A compound of two metals, e.g. Cu3Sn4.	48
I/O Interface – Ethernet PoE	288
Jacket: Outermost layer of insulating material of a cable.	107
J-Lead: A lead configuration in surface mount components where the lead exits a component and is formed into a reverse “j” shape with the base of the “j” contacting the solder pad.	150, 159
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Land: A metal coating on a printed circuit board to allow for mechanical or soldered contact.	150
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